

Description

The AP2301AI uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

 $V_{DS} = -20V I_{D} = -3.3A$

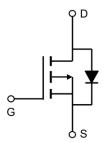
 $R_{DS(ON)}$ < 80m Ω @ V_{GS} =-4.5V

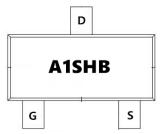
Application

Battery protection

Load switch

Uninterruptible power supply







Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AP2301AI	SOT-23	A1SHB	3000

Absolute Maximum Ratings (T_C=25°C unless otherwise noted)

Symbol	Parameter	Parameter Rating		
VDS	Drain-Source Voltage -20		V	
Vgs	Gate-Source Voltage	±12	V	
I _D @T _A =25°C	Continuous Drain Current, V _{GS} @ -4.5V ¹	-3.3	А	
I _D @T _A =70°C	Continuous Drain Current, V _{GS} @ -4.5V ¹	-2.6	А	
Ірм	Pulsed Drain Current ²	-13	А	
P _D @T _A =25°C	Total Power Dissipation ³	1.4	W	
Тѕтс	Storage Temperature Range	-55 to 150	°C	
TJ	Operating Junction Temperature Range	-55 to 150	°C	
R _θ JA	Thermal Resistance Junction-ambient ¹	125	°C/W	
R _θ JA	Thermal Resistance Junction-ambient¹(t≤10s)	90	°C/W	





Electrical Characteristics (T_J=25°C, unless otherwise noted)

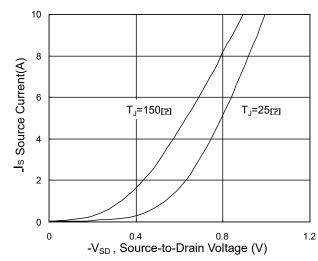
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BVDSS	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =-250uA	-20	-22		V	
RDS(ON)	Static Drain-Source On-Resistance ²	V _{GS} =-4.5V , I _D =-3A		55	80		
		V _{GS} =-2.5V , I _D =-2A		75	100	mΩ	
V _{GS(th)}	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=-250uA$	-0.5	-0.7	-1.2	V	
IDSS	Drain-Source Leakage Current	V _{DS} =-20V , V _{GS} =0V , T _J =25°C			-1	uA	
		V _{DS} =-20V , V _{GS} =0V , T _J =55°C			-5		
lgss	Gate-Source Leakage Current	V_{GS} = $\pm 12V$, V_{DS} = $0V$			±100	nA	
gfs	Forward Transconductance	V _{DS} =-5V , I _D =-3A		12.2		S	
Qg	Total Gate Charge (-4.5V)			10.1			
Qgs	Gate-Source Charge	V _{DS} =-15V , V _{GS} =-4.5V , I _D =-3A		1.21		nC	
Qgd	Gate-Drain Charge			2.46			
Td(on)	Turn-On Delay Time			5.6			
Tr	Rise Time	V_{DD} =-10V , V_{GS} =-4.5V ,		32.2			
Td(off)	Turn-Off Delay Time	$R_G=3.3\Omega$ $I_D=-3A$		45.6		ns	
T _f	Fall Time			29.2			
Ciss	Input Capacitance			677			
Coss	Output Capacitance	V _{DS} =-15V , V _{GS} =0V , f=1MHz		82		pF	
Crss	Reverse Transfer Capacitance			73			
Is	Continuous Source Current ^{1,4}	V _G =V _D =0V , Force Current			-3	Α	
VsD	Diode Forward Voltage ²	V _{GS} =0V , I _S =-1A , T _J =25°C			-1	V	

Note:

- 1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width $\leq 300 \text{us}$, duty cycle $\leq 2\%$
- 3. The power dissipation is limited by 150 $^{\circ}\mathrm{C}$ junction temperature
- 4. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



Typical Characteristics



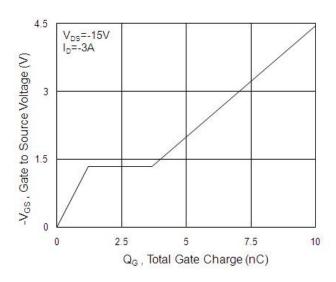


Fig.1 Typical Output Characteristics

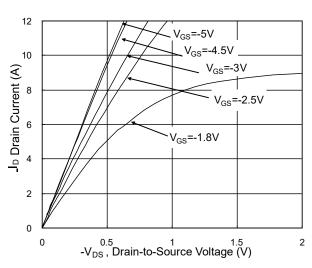
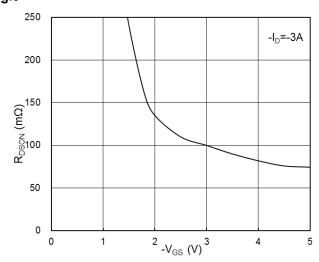


Fig.2 On-Resistance vs. G-S Voltage Fig.3



Source Drain Forward Characteristics

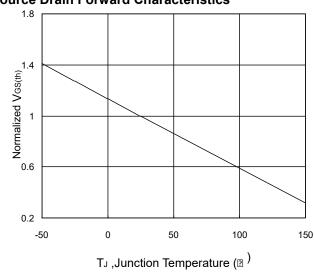
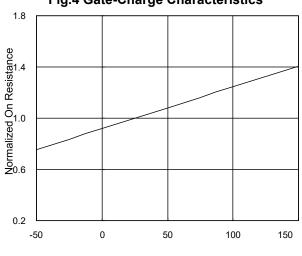
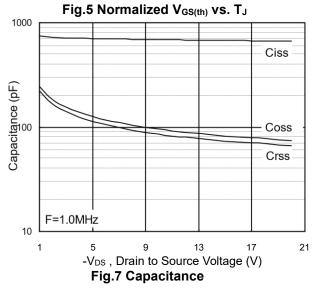
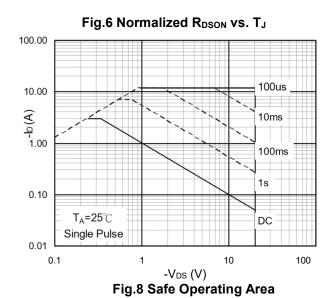


Fig.4 Gate-Charge Characteristics









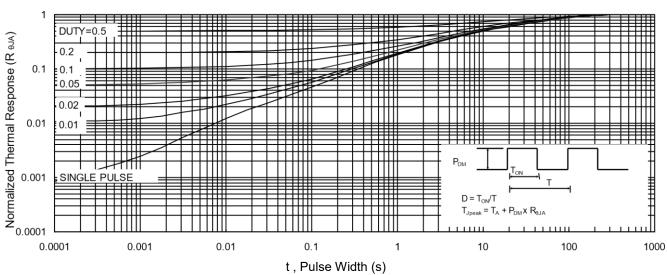
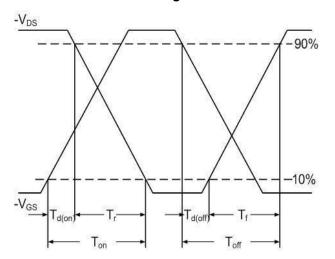


Fig.9 Normalized Maximum Transient Thermal Impedance



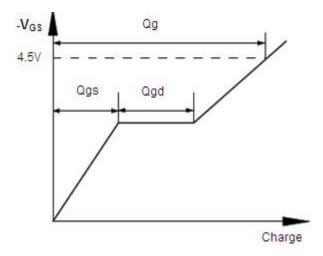
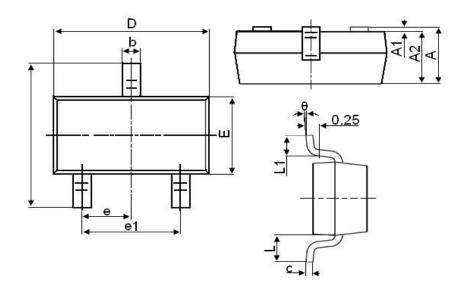


Fig.10 Switching Time Waveform

Fig.11 Gate Charge Waveform



Package Mechanical Data-SOT-23



Symbol	Dimensions in Millimeters		
	MIN.	MAX.	
А	0.900	1.150	
A1	0.000	0.100	
A2	0.900	1.050	
b	0.300	0.500	
С	0.080	0.150	
D	2.800	3.000	
E	1.200	1.400	
E1	2.250	2.550	
е	0.950TYP		
e1	1.800	2.000	
L	0.550REF		
L1	0.300	0.500	
θ	0°	8°	



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Edition	Date	Change
RVE1.2	2017/6/19	Initial release
RVE1.3	2020/8/19	Reduce RDS(on)

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